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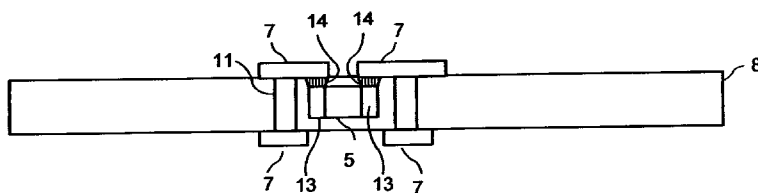


FIG. 2A

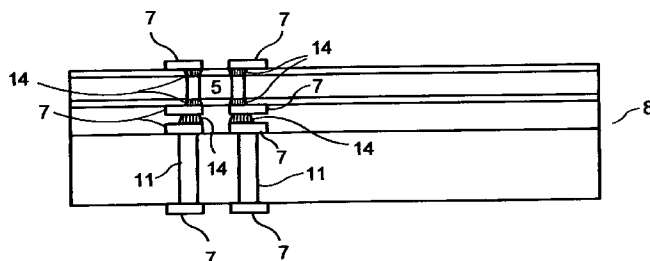


FIG. 2b

(57) Abstract: The present disclosure relates to embedding a power modification component such as a capacitance or a resistance inside of pads that are located to extend over and beyond the vias of the PCB so that a portion of the pad containing the embedded capacitance or resistance is located beyond where the vias or blinds are located. Each of the pads will include an opening that is located over a given one of the vias or blinds to permit that via to conduct through the opening. In this way the capacitance and the resistance will have a closer contact point the electrical component.